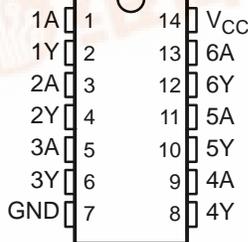


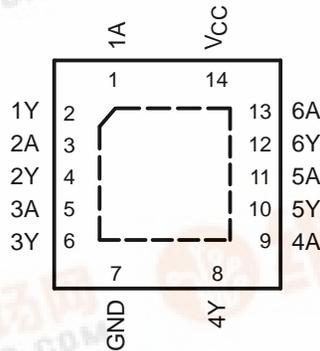
FEATURES

- Operate From 1.65 V to 3.6 V
- Specified From -40°C to 85°C , -40°C to 125°C , and -55°C to 125°C
- Inputs and Open-Drain Outputs Accept Voltages up to 5.5 V
- Max t_{pd} of 3.7 ns at 3.3 V
- I_{off} Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 250 mA Per JESD 17

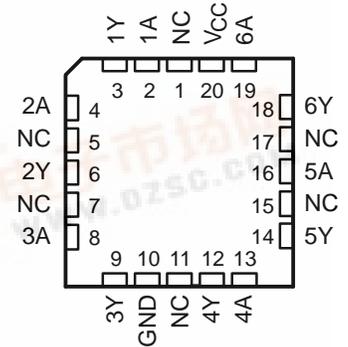
SN54LVC06A ... J OR W PACKAGE
SN74LVC06A ... D, DB, DGV, NS,
OR PW PACKAGE
(TOP VIEW)



SN74LVC06A ... RGY PACKAGE
(TOP VIEW)



SN54LVC06A ... FK PACKAGE
(TOP VIEW)



NC - No internal connection

DESCRIPTION/ORDERING INFORMATION

These hex inverter buffers/drivers are designed for 1.65-V to 3.6-V V_{CC} operation.

The outputs of the 'LVC06A devices are open drain and can be connected to other open-drain outputs to implement active-low wired-OR or active-high wired-AND functions. The maximum sink current is 24 mA.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

ORDERING INFORMATION

T_A	PACKAGE ⁽¹⁾		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QFN – RGY	Reel of 1000	SN74LVC06ARGYR	LC06A
		Tube of 50	SN74LVC06AD	LVC06A
-40°C to 125°C	SOIC – D	Reel of 2500	SN74LVC06ADR	
		Reel of 250	SN74LVC06ADT	
		SOP – NS	Reel of 2000	SN74LVC06ANSR
	SSOP – DB	Reel of 2000	SN74LVC06ADBR	LC06A
	TSSOP – PW	Tube of 90	SN74LVC06APW	LC06A
		Reel of 2000	SN74LVC06APWR	
		Reel of 250	SN74LVC06APWT	
TVSOP – DGV	Reel of 2000	SN74LVC06ADGVR	LC06A	
-55°C to 125°C	CDIP – J	Tube of 25	SNJ54LVC06AJ	SNJ54LVC06AJ
	CFP – W	Tube of 150	SNJ54LVC06AW	SNJ54LVC06AW
	LCCC – FK	Tube of 55	SNJ54LVC06AFK	SNJ54LVC06AFK

(1) Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

SN54LVC06A, SN74LVC06A HEX INVERTER BUFFERS/DRIVERS WITH OPEN-DRAIN OUTPUTS

SCAS596N–OCTOBER 1997–REVISED JULY 2005



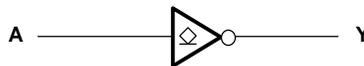
DESCRIPTION/ORDERING INFORMATION (CONTINUED)

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

**FUNCTION TABLE
(EACH INVERTER)**

INPUT A	OUTPUT Y
H	L
L	H

LOGIC DIAGRAM, EACH INVERTER (POSITIVE LOGIC)



Absolute Maximum Ratings⁽¹⁾

over operating free-air temperature range (unless otherwise noted)

		MIN	MAX	UNIT	
V_{CC}	Supply voltage range	-0.5	6.5	V	
V_I	Input voltage range ⁽²⁾	-0.5	6.5	V	
V_O	Output voltage range	-0.5	6.5	V	
I_{IK}	Input clamp current		$V_I < 0$	-50 mA	
I_{OK}	Output clamp current		$V_O < 0$	-50 mA	
I_O	Continuous output current		±50	mA	
	Continuous current through V_{CC} or GND		±100	mA	
θ_{JA}	Package thermal impedance	D package ⁽³⁾		86	°C/W
		DB package ⁽³⁾		96	
		DGV package ⁽³⁾		127	
		NS package ⁽³⁾		76	
		PW package ⁽³⁾		113	
	RGY package ⁽⁴⁾		47		
T_{stg}	Storage temperature range	-65	150	°C	
P_{tot}	Power dissipation ⁽⁵⁾⁽⁶⁾		$T_A = -40^\circ\text{C to } 125^\circ\text{C}$	500 mW	

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) The package thermal impedance is calculated in accordance with JESD 51-7.
- (4) The package thermal impedance is calculated in accordance with JESD 51-5.
- (5) For the D package: above 70°C the value of P_{tot} derates linearly with 8 mW/K.
- (6) For the DB, DGV, NS, and PW packages: above 60°C the value of P_{tot} derates linearly with 5.5 mW/K.

Recommended Operating Conditions⁽¹⁾

		SN54LVC06A ⁽²⁾		UNIT	
		–55°C to 125°C			
		MIN	MAX		
V _{CC}	Supply voltage	Operating	1.65	3.6	V
		Data retention only	1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		
		V _{CC} = 2.7 V to 3.6 V	2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		
V _I	Input voltage	0	5.5	V	
V _O	Output voltage	0	5.5	V	
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		mA
		V _{CC} = 2.3 V	8		
		V _{CC} = 2.7 V	12		
		V _{CC} = 3 V	24		

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.
(2) Product preview

Recommended Operating Conditions⁽¹⁾

		SN74LVC06A						UNIT	
		T _A = 25°C		–40°C to 85°C		–40°C to 125°C			
		MIN	MAX	MIN	MAX	MIN	MAX		
V _{CC}	Supply voltage	Operating	1.65	3.6	1.65	3.6	1.65	3.6	V
		Data retention only	1.5		1.5		1.5		
V _{IH}	High-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}		0.65 × V _{CC}		0.65 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	1.7		1.7		1.7		
		V _{CC} = 2.7 V to 3.6 V	2		2		2		
V _{IL}	Low-level input voltage	V _{CC} = 1.65 V to 1.95 V	0.35 × V _{CC}		0.35 × V _{CC}		0.35 × V _{CC}		V
		V _{CC} = 2.3 V to 2.7 V	0.7		0.7		0.7		
		V _{CC} = 2.7 V to 3.6 V	0.8		0.8		0.8		
V _I	Input voltage	0	5.5	0	5.5	0	5.5	V	
V _O	Output voltage	0	5.5	0	5.5	0	5.5	V	
I _{OL}	Low-level output current	V _{CC} = 1.65 V	4		4		4		mA
		V _{CC} = 2.3 V	8		8		8		
		V _{CC} = 2.7 V	12		12		12		
		V _{CC} = 3 V	24		24		24		

- (1) All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

SN54LVC06A, SN74LVC06A HEX INVERTER BUFFERS/DRIVERS WITH OPEN-DRAIN OUTPUTS

SCAS596N–OCTOBER 1997–REVISED JULY 2005



Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN54LVC06A ⁽¹⁾			UNIT
			–55°C to 125°C			
			MIN	TYP ⁽²⁾	MAX	
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V	0.2			V
	I _{OL} = 4 mA	1.65 V	0.45			
	I _{OL} = 8 mA	2.3 V	0.7			
	I _{OL} = 12 mA	2.7 V	0.4			
	I _{OL} = 24 mA	3 V	0.55			
I _I	V _I = 5.5 V or GND	3.6 V	±5			μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V	10			μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V	500			μA
C _i	V _I = V _{CC} or GND	3.3 V	5			pF

(1) Product preview

(2) T_A = 25°C

Electrical Characteristics

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	V _{CC}	SN74LVC06A						UNIT	
			T _A = 25°C			–40°C to 85°C		–40°C to 125°C		
			MIN	TYP	MAX	MIN	MAX	MIN		MAX
V _{OL}	I _{OL} = 100 μA	1.65 V to 3.6 V	0.1			0.2		0.3		V
	I _{OL} = 4 mA	1.65 V	0.24			0.45		0.6		
	I _{OL} = 8 mA	2.3 V	0.3			0.7		0.75		
	I _{OL} = 12 mA	2.7 V	0.4			0.4		0.6		
	I _{OL} = 24 mA	3 V	0.55			0.55		0.8		
I _I	V _I = 5.5 V or GND	3.6 V	±1			±5		±20		μA
I _{off}	V _I or V _O = 5.5 V	0	±1			±10		±20		μA
I _{CC}	V _I = V _{CC} or GND, I _O = 0	3.6 V	1			10		40		μA
ΔI _{CC}	One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V	500			500		5000		μA
C _i	V _I = V _{CC} or GND	3.3 V	5							pF

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN54LVC06A ⁽¹⁾		UNIT
				–55°C to 125°C		
				MIN	MAX	
t _{pd}	A	Y	1.8 V ± 0.15 V	1.4	5.6	ns
			2.5 V ± 0.2 V	1	3.1	
			2.7 V		3.9	
			3.3 V ± 0.3 V	1	3.7	

(1) Product preview

Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted) (see [Figure 1](#))

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC}	SN74LVC06A						UNIT	
				T _A = 25°C			–40°C to 85°C		–40°C to 125°C		
				MIN	TYP	MAX	MIN	MAX	MIN		MAX
t _{pd}	A	Y	1.8 V ± 0.15 V	1.4	3	5.1	1.4	5.6	1.4	7.6	ns
			2.5 V ± 0.2 V	1	1.9	2.8	1	3.1	1	4	
			2.7 V	1	2.4	3.7	1	3.9	1	5	
			3.3 V ± 0.3 V	1	2.2	3.5	1	3.7	1	5	

Operating Characteristics

T_A = 25°C

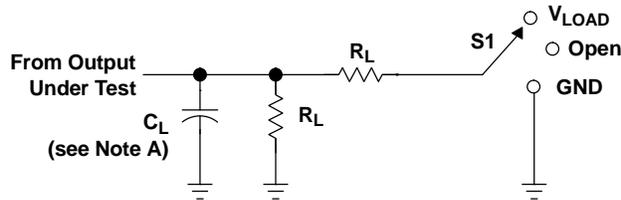
PARAMETER		TEST CONDITIONS	V _{CC}	TYP	UNIT
C _{pd}	Power dissipation capacitance per buffer/driver	f = 10 MHz	1.8 V	2.1	pF
			2.5 V	2.3	
			3.3 V	2.5	

SN54LVC06A, SN74LVC06A HEX INVERTER BUFFERS/DRIVERS WITH OPEN-DRAIN OUTPUTS

SCAS596N—OCTOBER 1997—REVISED JULY 2005



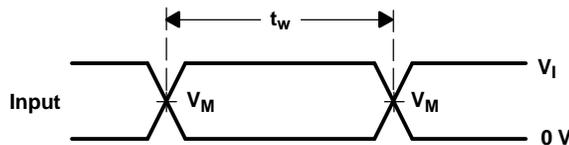
PARAMETER MEASUREMENT INFORMATION (OPEN DRAIN)



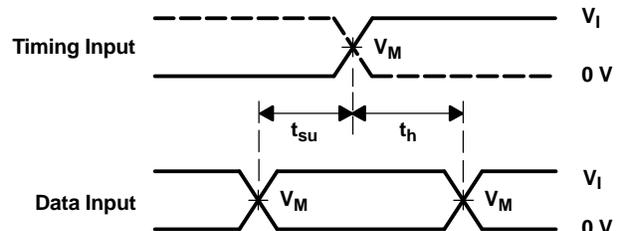
LOAD CIRCUIT

TEST	S1
t_{PZL} (see Notes E and F)	V_{LOAD}
t_{PLZ} (see Notes E and G)	V_{LOAD}
t_{PHZ}/t_{PZH}	V_{LOAD}

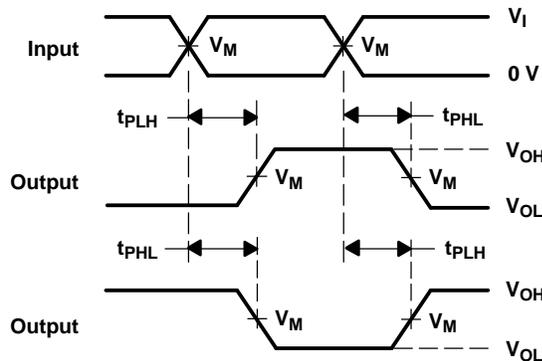
V_{CC}	INPUT		V_M	V_{LOAD}	C_L	R_L	V_{Δ}
	V_I	t_r/t_f					
$1.8\text{ V} \pm 0.15\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	1 k Ω	0.15 V
$2.5\text{ V} \pm 0.2\text{ V}$	V_{CC}	$\leq 2\text{ ns}$	$V_{CC}/2$	$2 \times V_{CC}$	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V
$3.3\text{ V} \pm 0.3\text{ V}$	2.7 V	$\leq 2.5\text{ ns}$	1.5 V	6 V	50 pF	500 Ω	0.3 V



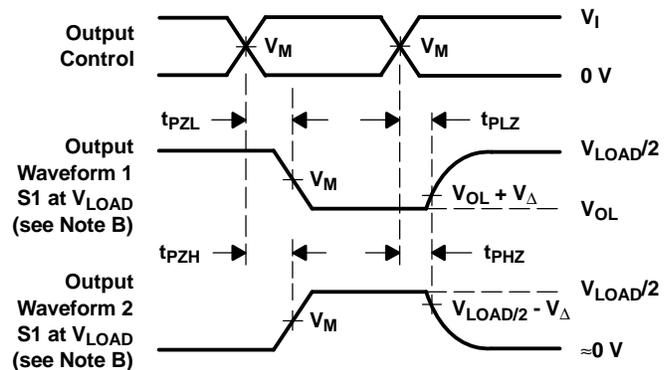
VOLTAGE WAVEFORMS
PULSE DURATION



VOLTAGE WAVEFORMS
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS
PROPAGATION DELAY TIMES
INVERTING AND NONINVERTING OUTPUTS



VOLTAGE WAVEFORMS
ENABLE AND DISABLE TIMES
LOW- AND HIGH-LEVEL ENABLING

- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10\text{ MHz}$, $Z_O = 50\ \Omega$.
 - The outputs are measured one at a time, with one transition per measurement.
 - Since this device has open-drain outputs, t_{PLZ} and t_{PZL} are the same as t_{pd} .
 - t_{PZL} is measured at V_M .
 - t_{PLZ} is measured at $V_{OL} + V_{\Delta}$.
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
SN74LVC06AD	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADBR	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADBRE4	ACTIVE	SSOP	DB	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADE4	ACTIVE	SOIC	D	14	50	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADGVR	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADGVRE4	ACTIVE	TVSOP	DGV	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADR	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADRE4	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADT	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ADTE4	ACTIVE	SOIC	D	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ANSR	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ANSRE4	ACTIVE	SO	NS	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APW	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWE4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWG4	ACTIVE	TSSOP	PW	14	90	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWLE	OBSOLETE	TSSOP	PW	14		TBD	Call TI	Call TI
SN74LVC06APWR	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWRE4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWRG4	ACTIVE	TSSOP	PW	14	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWT	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWTE4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06APWTG4	ACTIVE	TSSOP	PW	14	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LVC06ARGYR	ACTIVE	QFN	RGY	14	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1YEAR

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in

a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS) or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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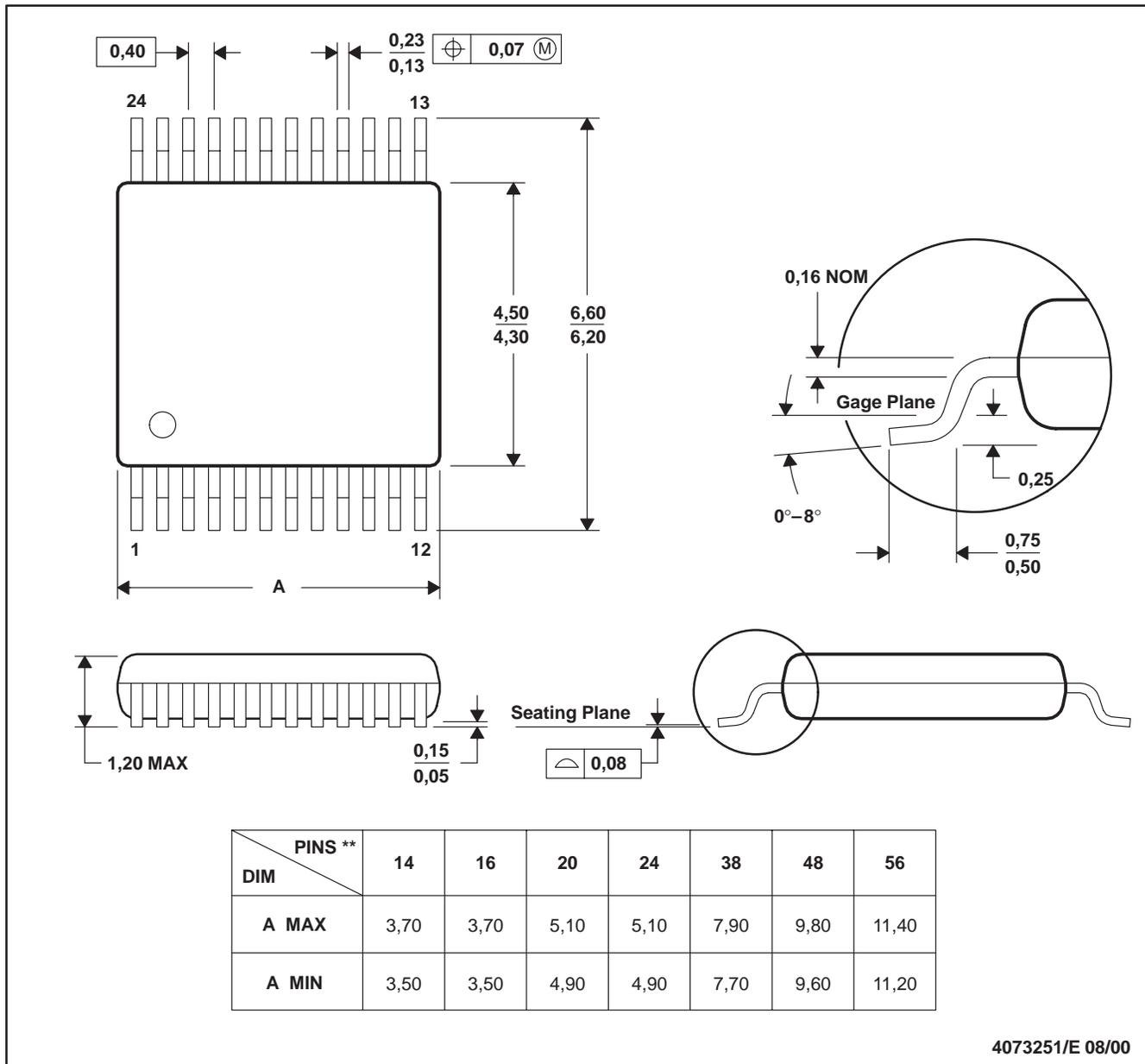
MECHANICAL DATA

MPDS006C – FEBRUARY 1996 – REVISED AUGUST 2000

DGV (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

24 PINS SHOWN

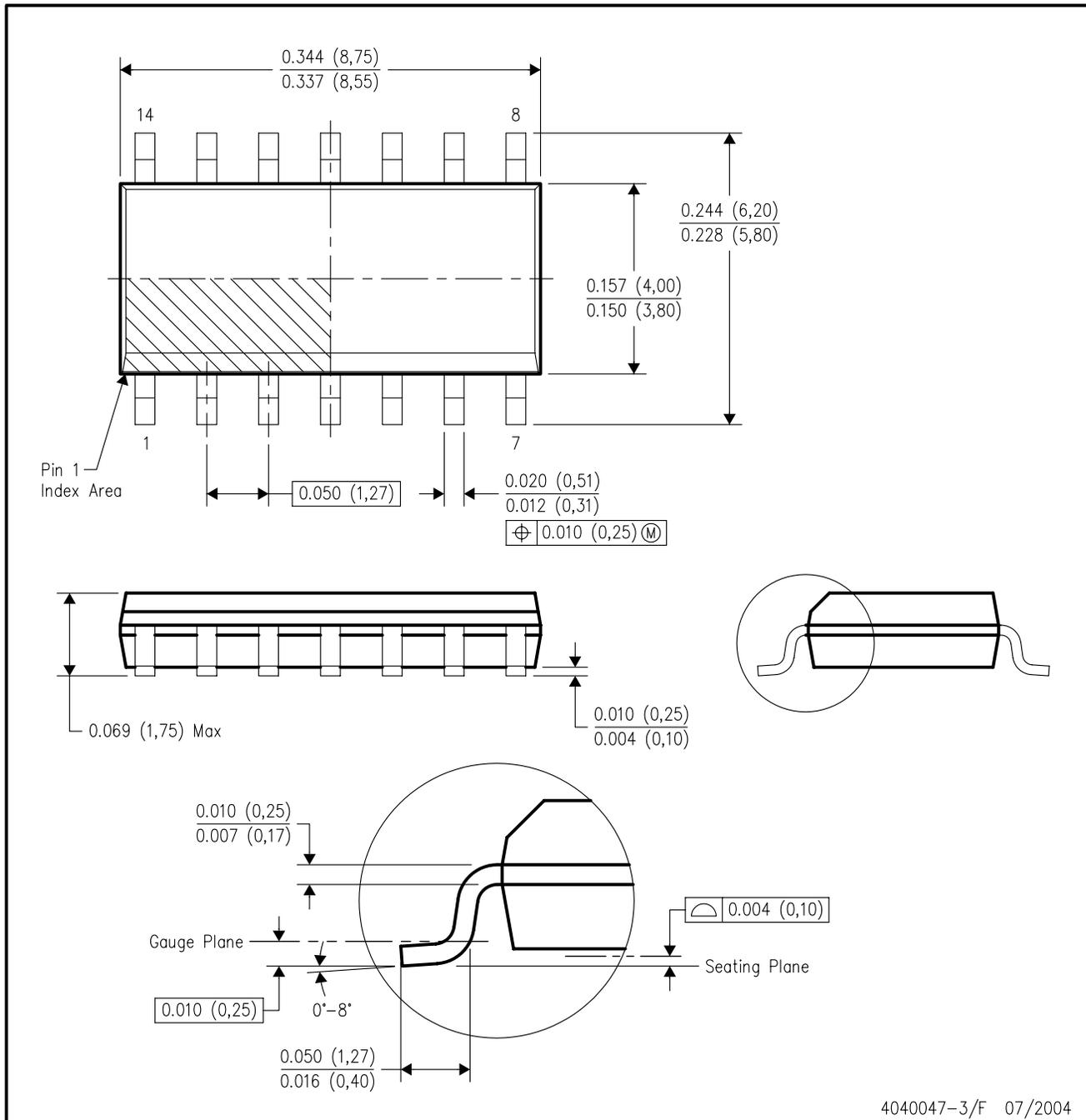


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.
 D. Falls within JEDEC: 24/48 Pins – MO-153
 14/16/20/56 Pins – MO-194

MECHANICAL DATA

D (R-PDSO-G14)

PLASTIC SMALL-OUTLINE PACKAGE

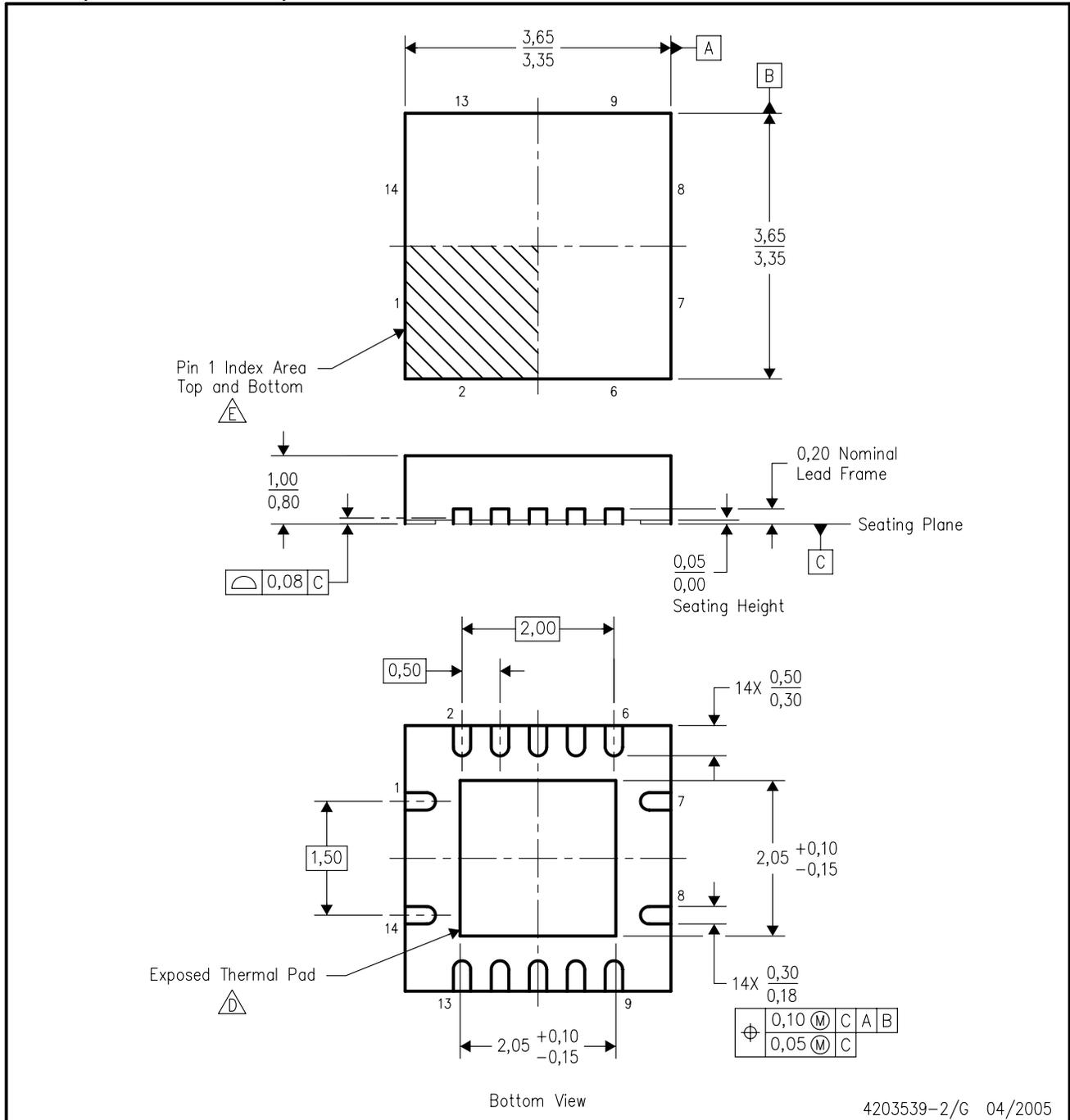


- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - Falls within JEDEC MS-012 variation AB.

MECHANICAL DATA

RGY (S-PQFP-N14)

PLASTIC QUAD FLATPACK



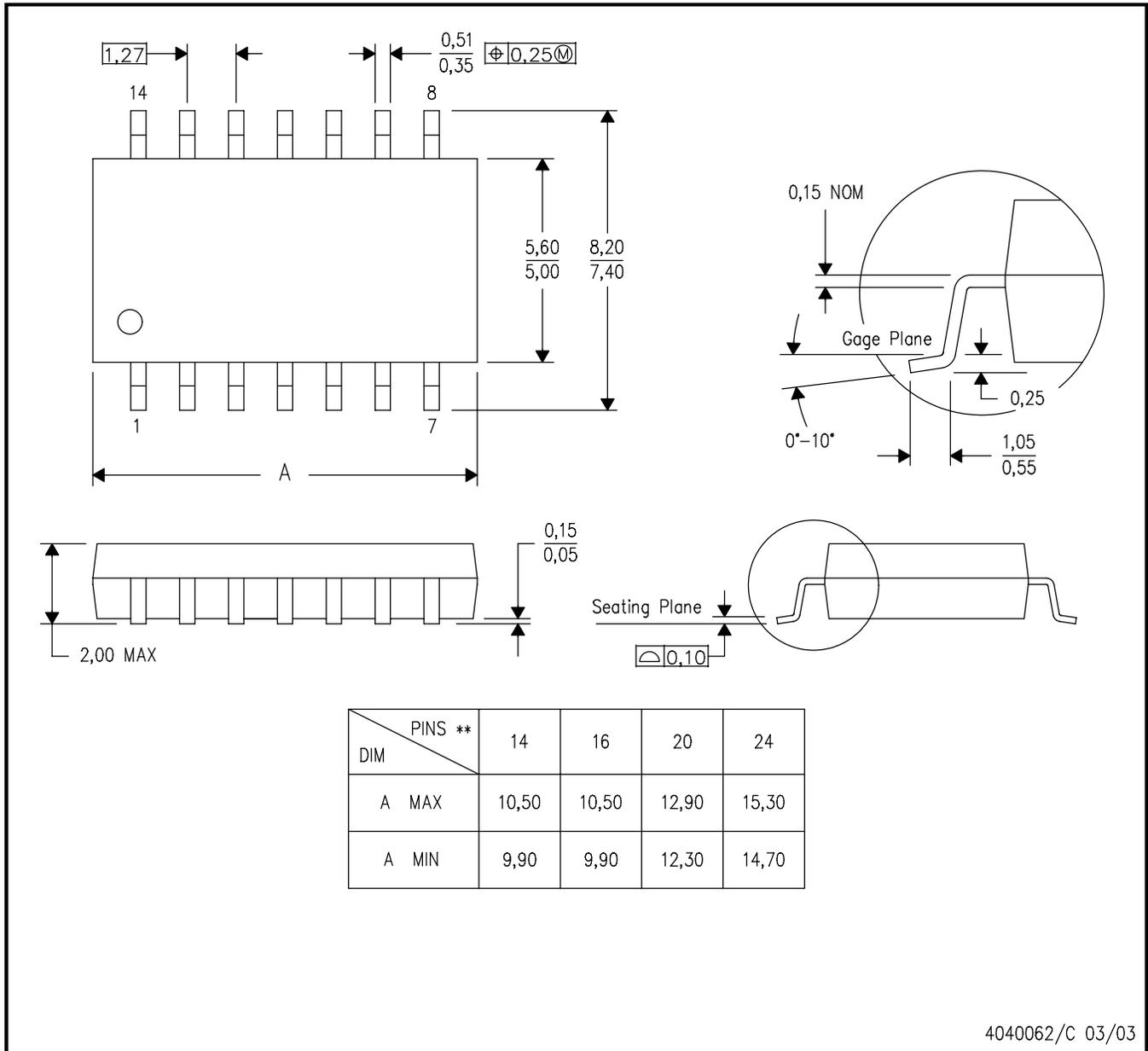
- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 - D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
 - E. Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BA.

MECHANICAL DATA

NS (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14-PINS SHOWN



4040062/C 03/03

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

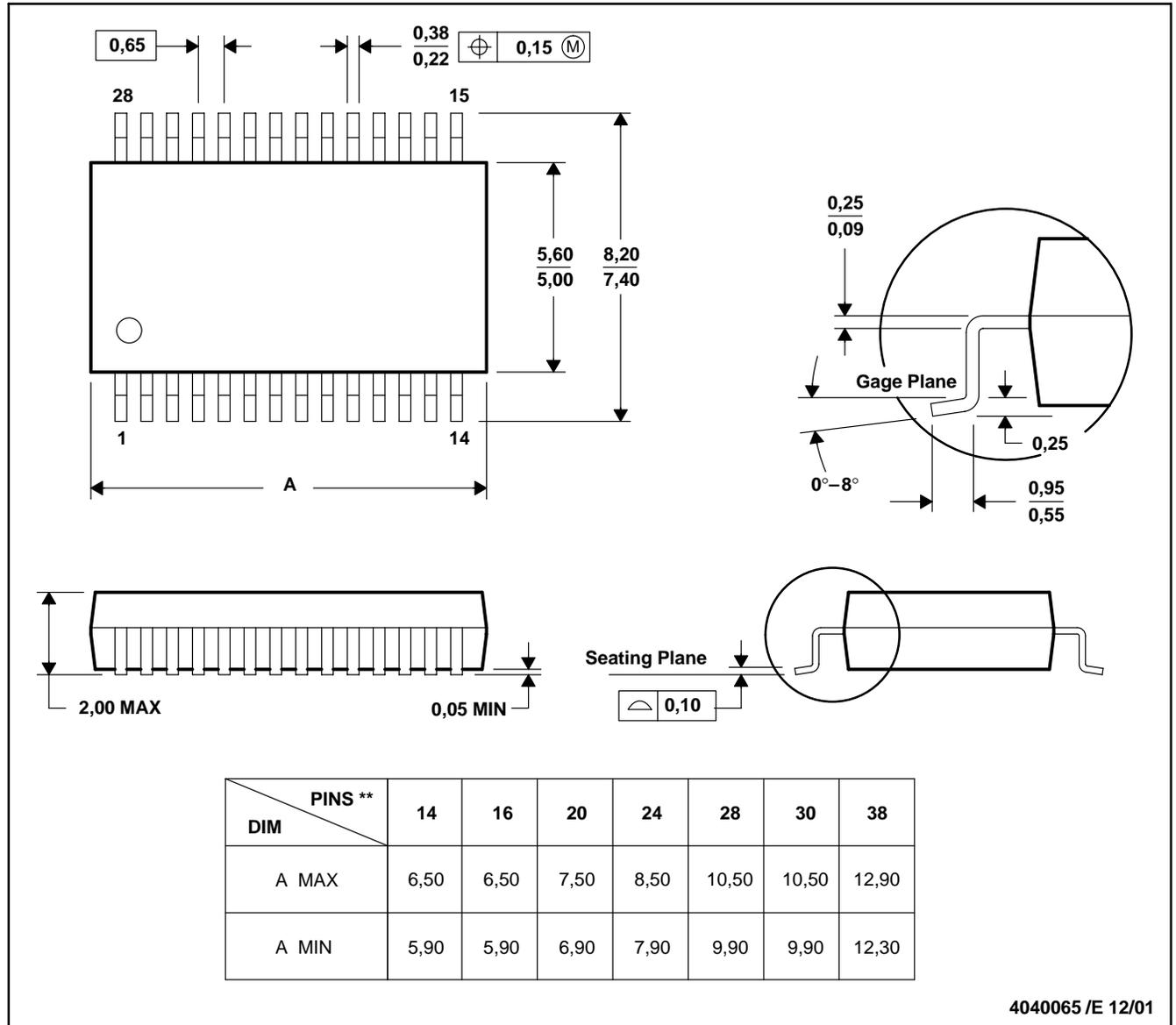
MECHANICAL DATA

MSS0002E – JANUARY 1995 – REVISED DECEMBER 2001

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

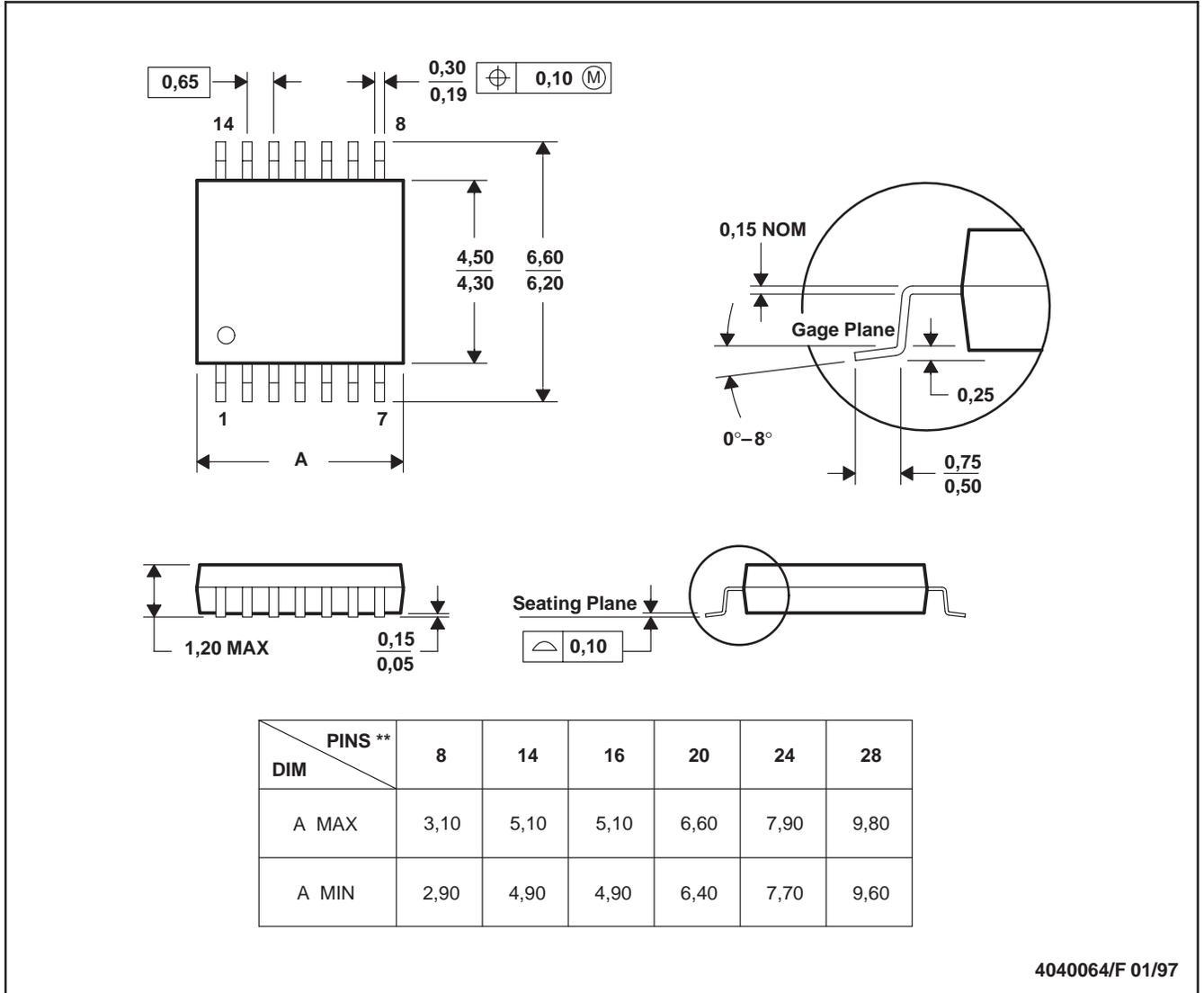
MECHANICAL DATA

MTSS001C – JANUARY 1995 – REVISED FEBRUARY 1999

PW (R-PDSO-G)**

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - D. Falls within JEDEC MO-153

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